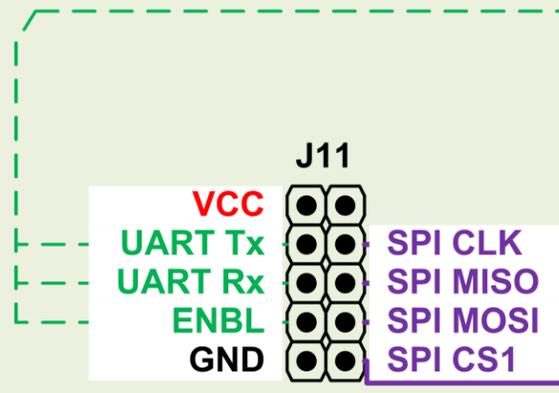
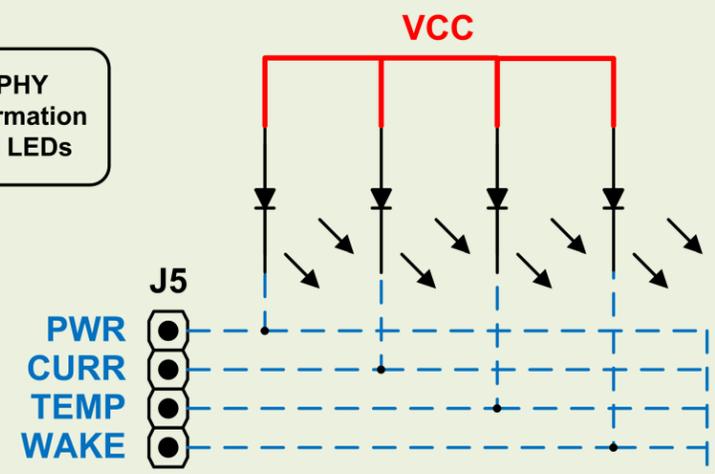
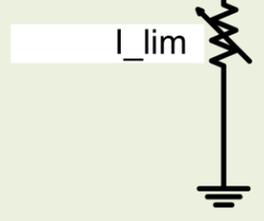
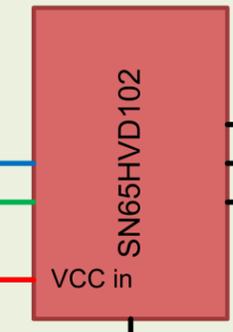
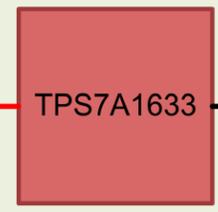
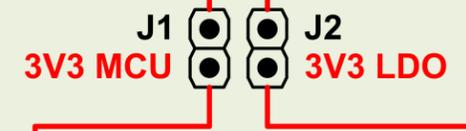
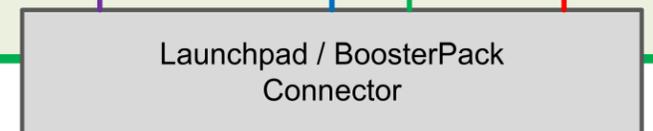


# TIDA-00339

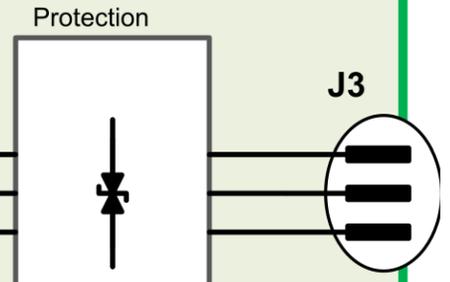
IO-Link PHY  
Status Information  
On J5 and LEDs



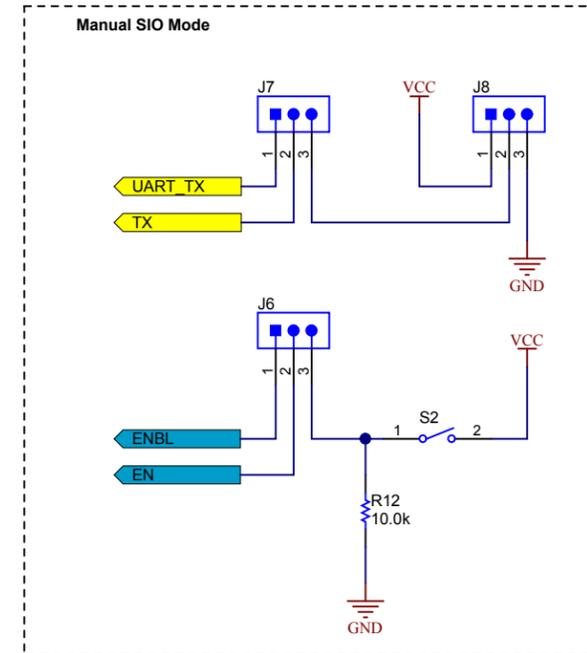
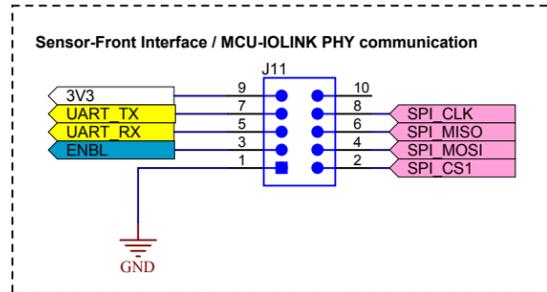
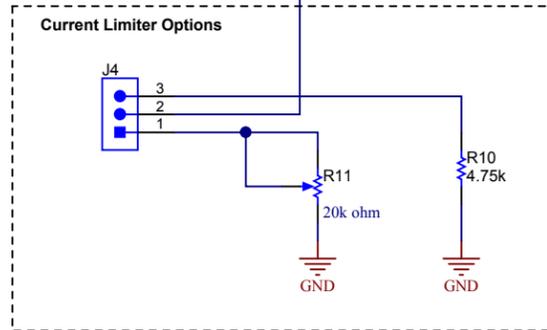
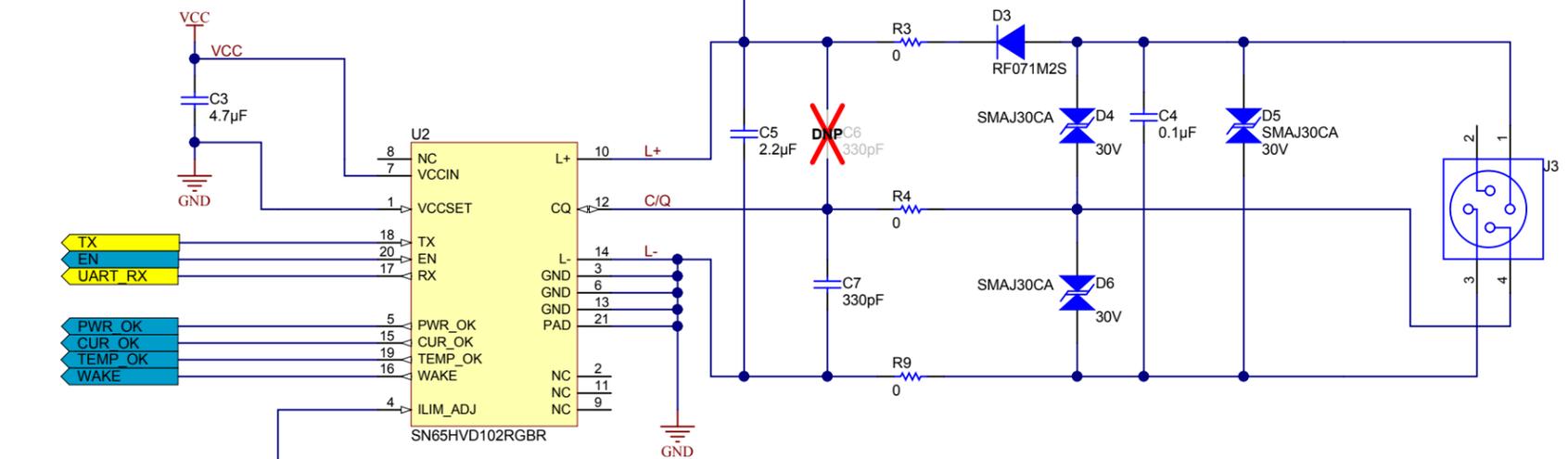
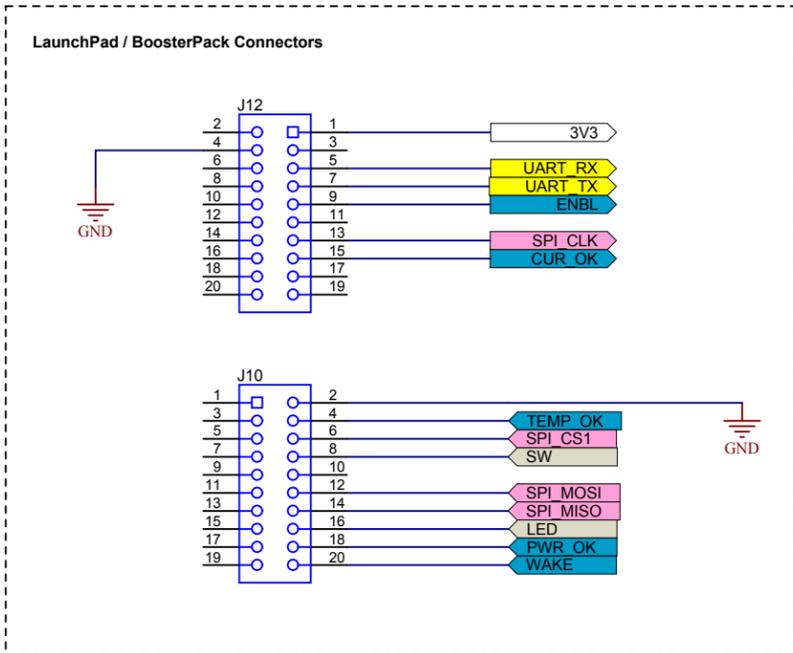
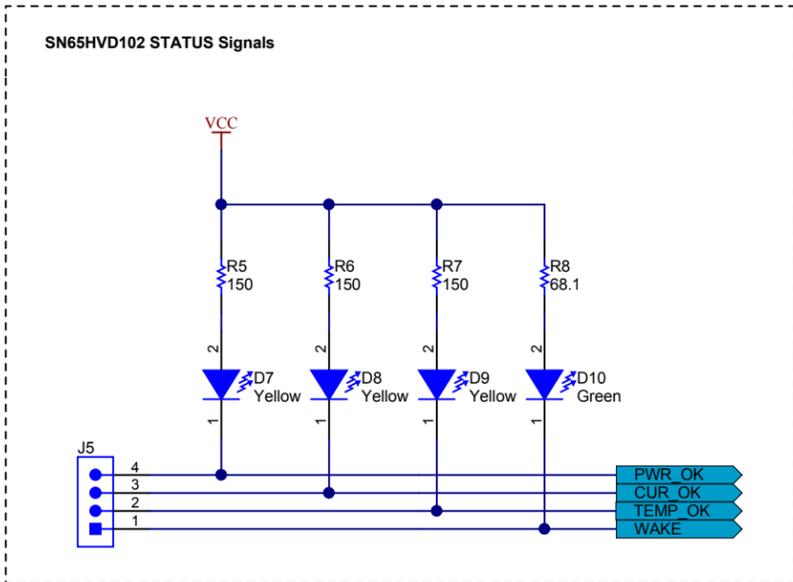
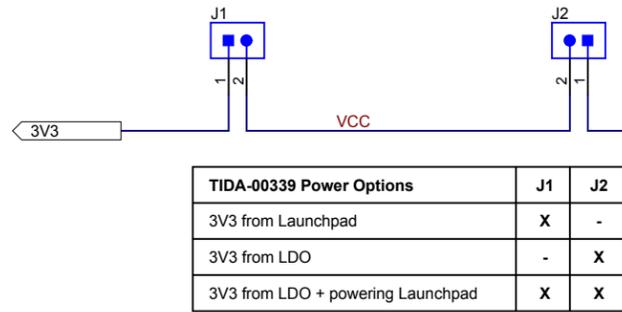
SPI/I2C for interfacing  
Sensor on J11  
Monitoring UART on J11



TIDA-00339 powered by	J1	J2
3V3 from Launchpad	X	-
3V3 from LDO	-	X
3V3 from LDO + powering Launchpad	X	X



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Orderable: N/A	Designed for: Public Release	Mod. Date: 12/1/2014
TID #: TIDA-00339	Project Title: Universal IO-Link	
Number: TIDA-00339	Rev: E1	Sheet Title: Universal IO-Link
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 3
Drawn By: AW	File: TIDA-00339_E1_BlankSheet.SchDoc	Size: B
Engineer: FA&C	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	



PCB  
LOGO  
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PCB Number: TIDA-00339  
PCB Rev: E1

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Label Table	
Variant	Label Text
001	001
002	002

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TID #: TIDA-00339	Project Title: Universal IO-Link		
Number: TIDA-00339	Rev: E1	Sheet Title: Hardware	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 3 of 3	
Drawn By: AW	File: TIDA-00339_E1_TID_Hardware.SchDoc	Size: B	
Engineer: FA&C	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>		

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